SILICON (Si) POWER MOSFET A CEP4060A



CET MOS

CEP4060A

60V ▲ 68mΩ ▲ 17A ▲ Si MOSFET

SILICON Si MOSFET ▲ THT type N-channel enhancement mode UL94V-0 rated flame retardant epoxy TO220-3L package Super high dense cell density for extremely low R_{DS(ON)} High power and current handling capability







MAXIMUM RATINGS

| Parameter (T _c = 25°C, unless otherwise noted) | Characteristics | |
|---|-----------------------------------|-----------------|
| Drain-Source Voltage | V _{DS} | 60V |
| Gate-Source Voltage | V _{GS} | ±20V |
| Continuous Drain Current at T _c = 25°C | I _D | 17A |
| Continuous Drain Current at T _c = 100°C | I _D | 12A |
| Pulsed Drain Current Note 1 | IDM Note 4 | 68A |
| Maximum Power Dissipation at T _c = 25°C | PD | 47W |
| Power Dissipation Derating above 25°C | ΔP _D | 0.3W/°C |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55°C to +175°C |

THERMAL CHARACTERISTICS

| Parameter | Symbol | Limit |
|---|--------------------|----------|
| Thermal Resistance, Junction-to-Case | R _{TH_JC} | 3.2°C/W |
| Thermal Resistance, Junction-to-Ambient | R _{th_ja} | 62.5°C/W |

APPLICATIONS

| Battery Management | DC/DC | DC | Industrial | Power |
|--------------------|-----------|------------|------------|----------|
| Systems | Converter | Fan | Control | Switches |
| + 4 - | | \bigcirc | | |

PIN DESCRIPTION

| Circuit Diagram | Outline - Front View | Pin No. | Description |
|-----------------|----------------------|---------|-------------|
| G (1) | | 1 | Gate |
| G (1) | | 2 | Drain |
| S (3) | | 3 | Source |

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ELECTRICAL CHARACTERISTICS A T_c = 25°C, unless otherwise noted

| ltem | Condition | Symbol | Min. | Тур. | Max. | Unit |
|---|---|---------------------|------|------|------|------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | $V_{GS} = 0V$, $I_D = 250\mu A$ | BV _{DSS} | 60 | | | V |
| Zero Gate Voltage Drain Current | $V_{DS} = 60V, V_{GS} = 0V$ | I _{DSS} | | | 25 | μΑ |
| Gate Body Leakage Current, Forward | $V_{GS} = 20V, V_{DS} = 0V$ | I _{GSSF} | | | 100 | nA |
| Gate Body Leakage Current, Reverse | V_{GS} = -20V, V_{DS} = 0V | I _{GSSR} | | | -100 | nA |
| On Characteristics Note 2 | | | | | | |
| Gate Threshold Voltage | $V_{GS} = V_{DS}$, $I_D = 250 \mu A$ | V _{GS(th)} | 2 | 2.7 | 4 | V |
| Static Drain-Source On-Resistance | V_{GS} = 10V, I_{D} = 7.5A | R _{DS(ON)} | | 68 | 85 | mΩ |
| Dynamic Characteristics Note 3 | | | | | | |
| Input Capacitance | V_{DS} = 25V, V_{GS} = 0V, f = 1MHz | CISS | | 410 | | рF |
| Output Capacitance | V_{DS} = 25V, V_{GS} = 0V, f = 1MHz | Coss | | 115 | | pF |
| Reverse Transfer Capacitance | V_{DS} = 25V, V_{GS} = 0V, f = 1MHz | C _{RSS} | | 20 | | pF |
| Switching Characteristics Note 3 | | | | | | |
| Turn-On Delay Time | V_{DD} = 30V, V_{GS} = 10V, I_D = 15A, $R_{G(ext)}$ = 25 Ω | t _{D(ON)} | | 12.4 | 24.8 | ns |
| Turn-On Rise Time | V_{DD} = 30V, V_{GS} = 10V, I_D = 15A, $R_{G(ext)}$ = 25 Ω | t _R | | 2 | 4 | ns |
| Turn-Off Delay Time | V_{DD} = 30V, V_{GS} = 10V, I_{D} = 15A, $R_{\text{G(ext)}}$ = 25 Ω | t _{D(OFF)} | | 24 | 48 | ns |
| Turn-Off Fall Time | V_{DD} = 30V, V_{GS} = 10V, I_{D} = 15A, $R_{\text{G(ext)}}$ = 25 Ω | t _F | | 6 | 12 | ns |
| Total Gate Charge | V_{DS} = 48V, V_{GS} = 10V, I_{D} = 15A | Q _G | | 8.1 | 10.5 | nC |
| Gate Source Charge | $V_{DS} = 48V, V_{GS} = 10V, I_D = 15A$ | Q _{GS} | | 1.6 | | nC |
| Gate Drain Charge | $V_{DS} = 48V, V_{GS} = 10V, I_D = 15A$ | Q _{GD} | | 2.4 | | nC |
| Drain-Source Diode Characteristics a | nd Maximum Ratings | | | | | |
| Drain-Source Diode Forward Current | | Is | | | 17 | А |
| Drain-Source Diode Forward Voltage ^{Note 2} | V _{GS} = 0V, I _S = 7.5A | V_{SD} | | 0.8 | 1.2 | V |

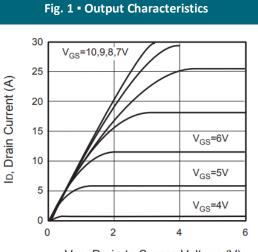
Notes

- 1: Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2: Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.
- 3: Guaranteed by design, not subject to production testing.
- 4: Pulse width limited by safe operating area.



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REFERENCE DATA ▲ TYPICAL DEVICE PERFORMANCE



VDS, Drain-to-Source Voltage (V)

Fig. 3 - Capacitance

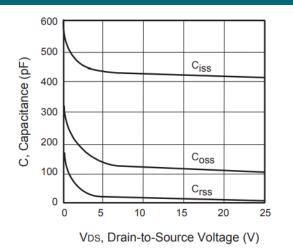
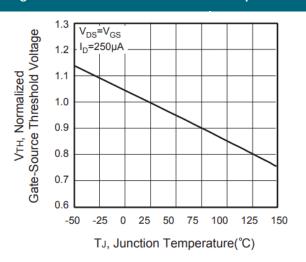


Fig. 5 - Gate Threshold Variation with Temperature



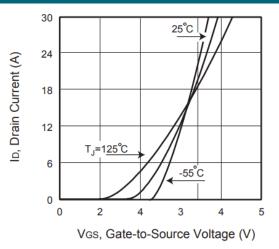


Fig. 2 • Transfer Characteristics

Fig. 4 • On-Resistance Variation with Temperature

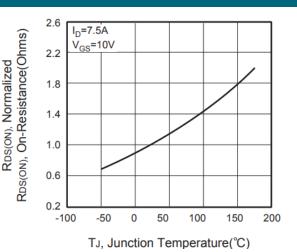
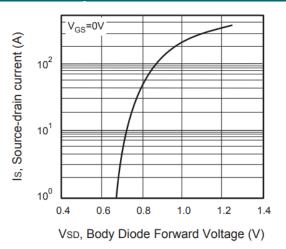


Fig. 6 - Body Diode Forward Voltage Variation

with Source Current



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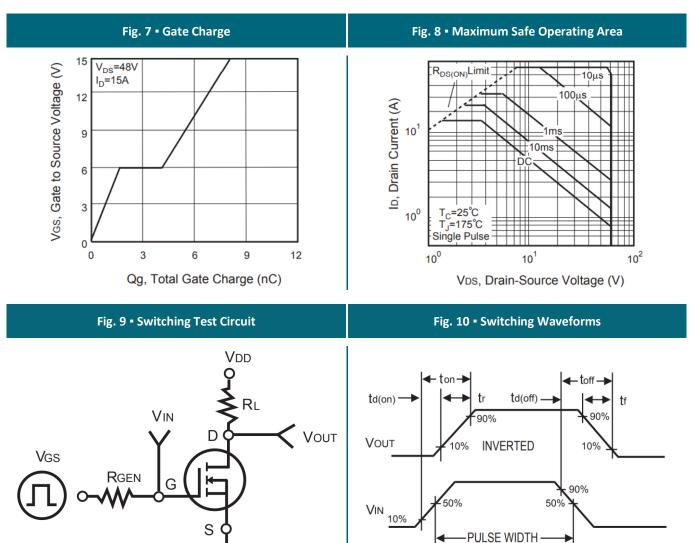
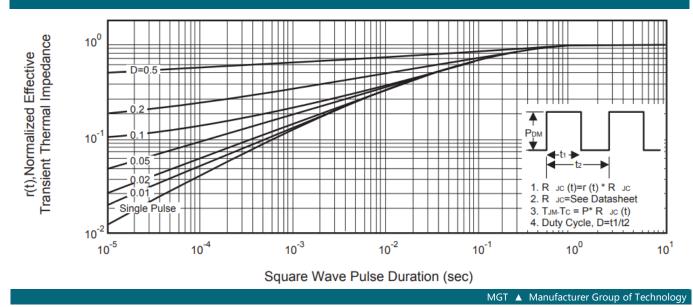


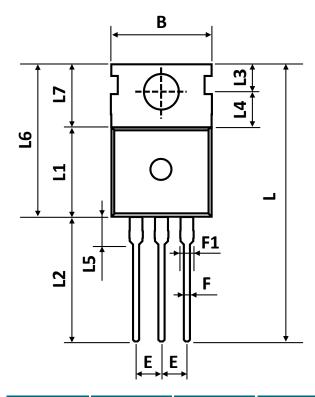
Fig. 11 • Normalized Thermal Transient Impedance Curve

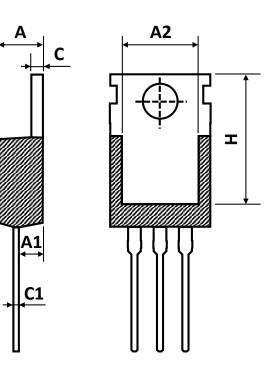


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PACKAGE OUTLINE





| Sym | Millimeters (Min.) | Millimeters (Typ.) | Millimeters (Max.) |
|-----|-----------------------|-----------------------|-----------------------|
| А | 4.43 | 4.53 | 4.63 |
| A1 | 2.30 | 2.40 | 2.50 |
| A2 | 7.70 | 7.90 | 8.10 |
| В | 9.80 | 10.00 | 10.20 |
| С | 1.25 | 1.30 | 1.40 |
| C1 | 0.45 | 0.50 | 0.60 |
| D | 3.45 | 3.60 | 3.70 |
| E | 2.45 | 2.54 | 2.60 |
| F | 0.70 | 0.80 | 0.95 |
| F1 | 1.15 | 1.33 | 1.50 |
| L | 26.80 | 28.80 | 30.80 |
| L1 | 9.20 | 9.30 | 9.40 |
| L2 | 12.80 | 13.10 | 13.40 |
| L3 | 2.70 | 2.80 | 2.90 |
| L4 | 3.50 | 3.70 | 3.80 |
| L5 | 2.60 | 2.90 | 3.20 |
| L6 | 15.40 | 15.80 | 16.20 |
| L7 | 6.20 | 6.50 | 6.80 |
| Н | 12.95 | 13.25 | 13.55 |

ORDERING INFORMATION

| Part Number | Package | Packing | Tube Qty. | Inner Box Qty. | Outer Box Qty. |
|-------------|-----------|---------|-----------|-----------------|-------------------------|
| CEP4060A | TO-220-3L | Tube | 50pcs | 1,000pcs | 4,000pcs |
| | | | | MGT 🔺 Manufactu | rer Group of Technology |

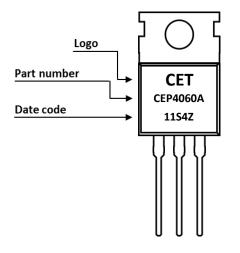
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PART MARKING



DATE CODE

Example: 11S4Z



| Product Type Z: Pb-free G: Green Product

| | Coding list for "Day" | | | | | | | | |
|----------------|-----------------------|----------|----------|----------|----------|----------|----------|----------|----------|
| 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | A |
| 01 | 02 | 03 | 04 | 05 | 06 | 07 | 08 | 09 | 10 |
| B | C | D | E | F | G | H | ┃ | J | K |
| 11 | 12 | 13 | 14 | 15 | 16 | 17 | 18 | 19 | 20 |
| L | M | N | 0 | P | Q | R | S | T | U |
| 21 | 22 | 23 | 24 | 25 | 26 | 27 | 28 | 29 | 30 |
| V 31 | | | | | | | | | |

Coding list for "Month"

| 1 Jan | 2 Feb | | | 5 May | |
|-----------------|-----------------|----------|----------|----------|----------|
| 7 | 8 | 9 | A | B | C |
| Jul | Aug | Sep | Oct | Nov | Dec |

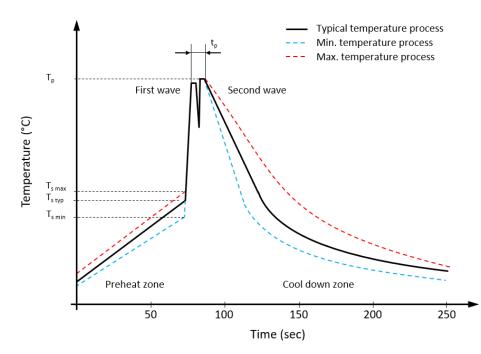
Coding list for "Year"







RECOMMENDED WAVE SOLDERING PROFILE ▲ THT PACKAGE



Classification wave soldering profile ▲ Refer to EN 61760-1: 2006

| Profile Features | | Value 🛦 Sn-Pb Assembly | Value 🔺 Pb-free Assembly |
|--|--------------------|--|--|
| Preheat temperature min. | $T_{s min}$ | 100 °C | 100 °C |
| Preheat temperature typical | T _{s typ} | 120 °C | 120 °C |
| Preheat temperature max. | $T_{s max}$ | 130 °C | 130 °C |
| Preheat time t_s from $T_{s min}$ to $T_{s max}$ | ts | 70 seconds | 70 seconds |
| Peak temperature | Tp | 235 °C to 260 °C | 245 °C to 260 °C |
| Time of actual peak temperature | t _p | Max. 10 seconds Max. 5 second each wave | Max. 10 seconds Max. 5 second each wave |
| Ramp-down date min. | | ~ 2 °C/second | ~ 2 °C/second |
| Ramp-down rate typical | | ~ 3.5 °C/second | ~ 3.5 °C/second |
| Ramp-down rate max. | | ~ 5 °C/second | ~ 5 °C/second |
| Time 25°C to 25°C | | 4 minutes | 4 minutes |



REVISION TABLE

| Revision | Date | Status | Notes |
|----------|------------|-----------------|---------------------|
| 001 | 30/09/2022 | Initial release | Initial publication |
| | | | |
| | | | |
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